

ABSTRACT OF THE DISCLOSURE

A method for forming a pattern using a printing process is disclosed in the present invention. The method includes forming a resist layer on a substrate having an etching layer thereon, locating a master having a convex pattern over the substrate, pressing the master against the substrate until the convex pattern of the master directly contacts the etching layer, and removing a portion of the resist layer to expose a surface over the substrate, the removed portion of the resist layer having a width substantially the same as the convex portion of the master.